



Inductors

RF chokes, BC+ series

Series/Type: **B78108E, B78148E**

Date: July 2015

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BC chokes

Rated inductance 0.1 μH ... 100 μH

Rated current 640 mA .. 7300 mA

Construction

- Ferrite drum core
- Winding: enamel copper wire
- Flame-retardant lacquer coating

Features

- Very high rated current
- High saturation behaviour
- High self-resonance frequency
- Suitable for wave soldering
- RoHS-compatible

Applications

- DC-DC converter
- Filtering of supply voltage & battery charger (EMI)
- RF blocking and filtering
- Decoupling and interference suppression
- For telecommunications, LED and energy-saving lamps, solar LED lamps, entertainment electronics

Terminals

- Radially bent to 5mm lead spacing (B78148E)
- Central axial leads (B78108E)
- Base material Cu
- Electroplated with nickel and pure tin

Marking

- Inductance indicated by color bands in accordance with IEC 60062

Delivery mode and packing units

- Taped, Ammo and reel packing
- Packing units:

| | Ammo (pcs./pack.) | Reel (pcs./reel) |
|--------|----------------------|---------------------|
| Axial | 2500 | 5000 |
| Radial | 2500 | 2000 |



B78108E



B78148E

Dimensional drawings
B78108E (axial leads, taped) Dimensions in mm

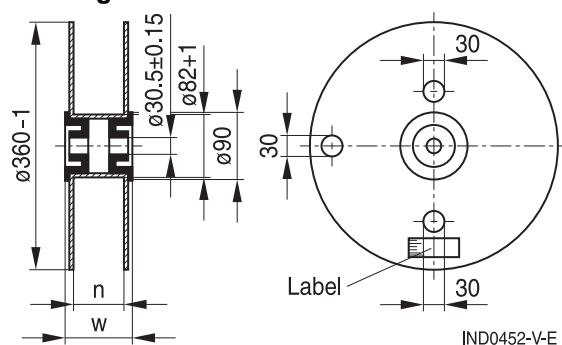
 IND0429-B-E **Minimum lead spacing 12.5 mm**
B78148E (central radial leads, taped)

Dimensions in mm



IND1244-N-E

IND0629-B

Packing


IND0452-V-E

Dimensions in mm



IND0631-B-E

 n (mm): axial 72 + 1, radial 42 + 1
 w (mm): axial 84 max., radial 54 max.

 L x W x H (max. mm):
 axial: 275 x 80 x 140, radial: 340 x 50 x 210

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Technical data and measuring conditions

| | |
|---|---|
| Rated inductance L_R | Measured with LCR meter Agilent 4284A or impedance analyzer Agilent 4294A Measuring current: 1 mA Measuring temperature: +20 °C |
| Q factor Q_{\min} | Measured with impedance analyzer Agilent 4294A, +20 °C |
| Rated temperature T_R | +40 °C |
| Rated current I_R | Maximum permissible DC current based on rated temperature of +40 °C and component temperature of max. +125 °C |
| Saturation current I_{sat} | Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%, at +20 °C (Agilent 4284A and 42841A) |
| DC resistance R_{\max} | Measured at +20 °C |
| Resonance frequency $f_{\text{res},\min}$ | Measured with Agilent 4294A or 8753ES, +20 °C |
| Solderability (lead-free) | Sn95.5Ag3.8Cu0.7: (+245 ±5) °C, (3 ±0.3) s Wetting of soldering area: ≥ 90% (to IEC 60068-2-20, test Ta) |
| Resistance to soldering heat | (+260 ±5)°C, 10 s (to IEC 60068-2-20, test Tb) |
| Tensile strength of leads | ≥ 20 N (to IEC 60068-2-21, test Ua) |
| Climatic category | 55/125/56 (to IEC 60068-1) |
| Storage conditions | Mounted: -55 °C ... +125 °C Packaged: -25 °C ... +40 °C, ≤ 75% RH |
| Weight | Approx. 0.38 g |


Mounting information:

When bending the leads, take care that the start-of-winding areas at the face ends (protected by glue and lacquer) are not subjected to any mechanical stress.

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Characteristics and ordering codes

| L _R μH | Tolerance | f _L MHz | Q _{min} | f _Q MHz | I _R mA | I _{sat} mA | R _{max} Ω | f _{res, min} MHz | Ordering code ¹⁾ (reel packing) ²⁾ |
|----------------------|-----------|-----------------------|------------------|-----------------------|----------------------|------------------------|-----------------------|------------------------------|---|
| 0.1 | ±20% ≐ M | 1.0 | 50 | 7.96 | 7300 | 17000 | 0.015 | 700 | B781*8E1101M000 |
| 0.15 | | 1.0 | 50 | 7.96 | 6500 | 14500 | 0.017 | 650 | B781*8E1151M000 |
| 0.22 | | 1.0 | 55 | 7.96 | 5900 | 12200 | 0.019 | 610 | B781*8E1221M000 |
| 0.33 | | 1.0 | 60 | 7.96 | 5300 | 10100 | 0.023 | 480 | B781*8E1331M000 |
| 0.47 | | 1.0 | 60 | 7.96 | 5000 | 8500 | 0.027 | 400 | B781*8E1471M000 |
| 0.68 | | 1.0 | 60 | 7.96 | 4600 | 7100 | 0.031 | 360 | B781*8E1681M000 |
| 1.0 | ±10% ≐ K | 1.0 | 60 | 7.96 | 4150 | 5800 | 0.038 | 260 | B781*8E1102K000 |
| 1.5 | | 1.0 | 60 | 7.96 | 3800 | 4800 | 0.047 | 235 | B781*8E1152K000 |
| 2.2 | | 1.0 | 50 | 7.96 | 3400 | 4000 | 0.057 | 150 | B781*8E1222K000 |
| 3.3 | | 1.0 | 45 | 7.96 | 3050 | 3250 | 0.073 | 75 | B781*8E1332K000 |
| 4.7 | | 1.0 | 45 | 7.96 | 2750 | 2700 | 0.085 | 35 | B781*8E1472K000 |
| 6.8 | | 1.0 | 40 | 7.96 | 2450 | 2300 | 0.105 | 25 | B781*8E1682K000 |
| 10 | | 1.0 | 35 | 7.96 | 2250 | 2000 | 0.136 | 20 | B781*8E1103K000 |
| 15 | | 0.1 | 40 | 0.796 | 1600 | 1450 | 0.230 | 15 | B781*8E1153K000 |
| 22 | 0.1 | 40 | 0.796 | 1300 | 1250 | 0.350 | 12 | B781*8E1223K000 | |
| 33 | ±5% ≐ J | 0.1 | 50 | 0.796 | 1050 | 1000 | 0.550 | 9.0 | B781*8E1333J000 |
| 47 | | 0.1 | 40 | 0.796 | 950 | 870 | 0.680 | 8.0 | B781*8E1473J000 |
| 68 | | 0.1 | 45 | 0.796 | 780 | 720 | 0.900 | 6.5 | B781*8E1683J000 |
| 100 | | 0.1 | 60 | 0.796 | 640 | 580 | 1.450 | 6.0 | B781*8E1104J000 |

1) Replace the * by code number "0" for axial taping or by "4" for radial taping.

2) For Ammo pack the last digit has to be a "9". Example: B78108E1223K009

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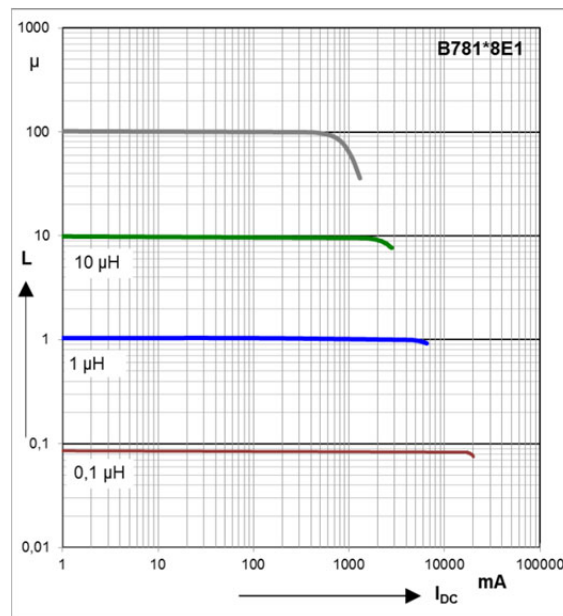
Impedance $|Z|$ versus frequency f

measured with impedance analyzer Agilent 4294A or S-parameter network analyzer Agilent 8753ES, typical values at +20 °C



Inductance L versus DC load current I_{DC}

measured with LCR meter Agilent 4284A and 42841A, typical values at +20 °C



Q factor versus frequency f

measured with impedance analyzer Agilent 4294A, typical values at +20 °C



Current derating I_{op}/I_R versus ambient temperature T_A

(rated temperature $T_R = +40$ °C)



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation. Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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